

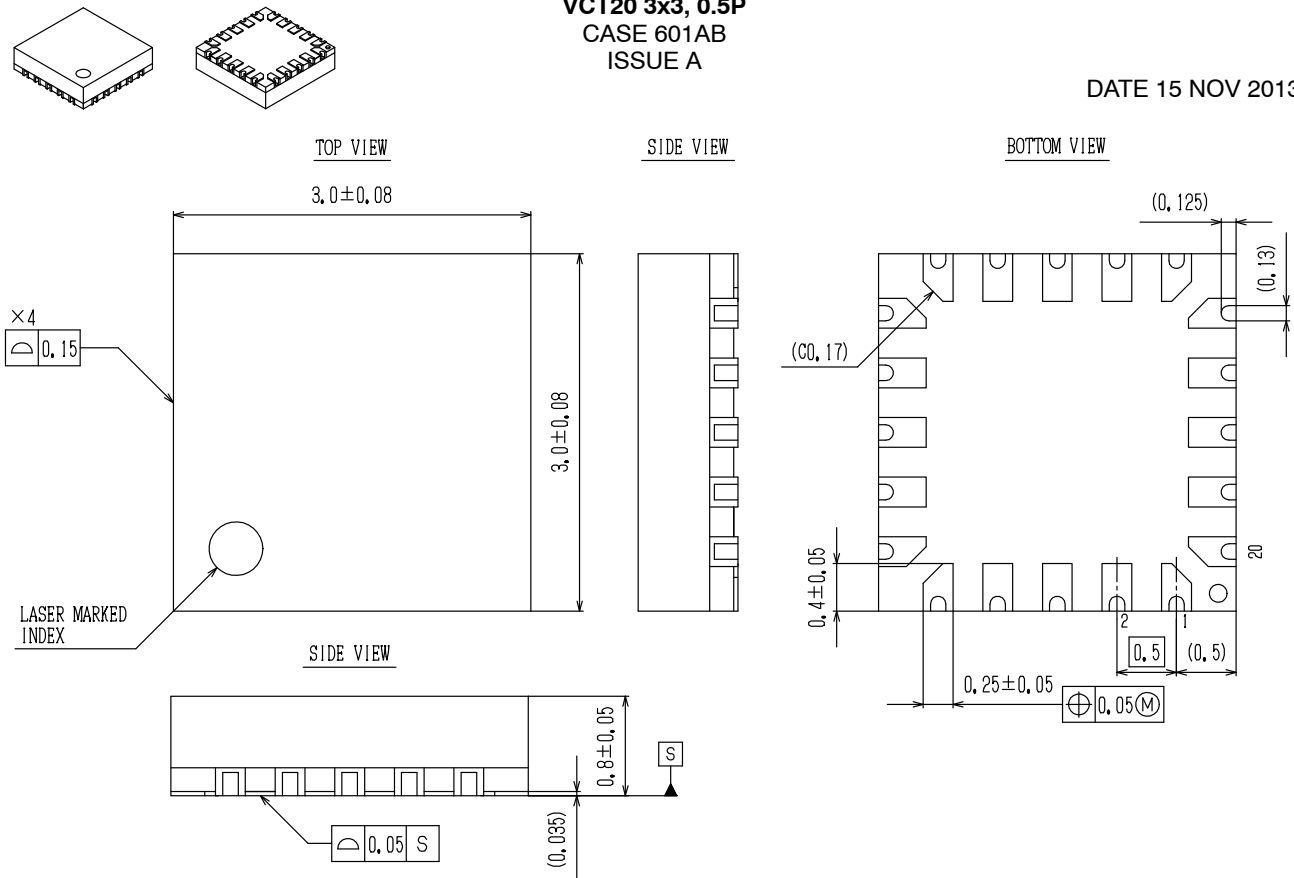
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

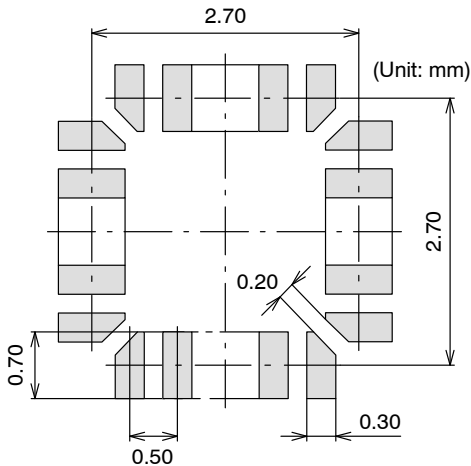


## VCT20 3x3, 0.5P CASE 601AB ISSUE A

DATE 15 NOV 2013



### SOLDERING FOOTPRINT\*



### GENERIC MARKING DIAGRAM\*



XXXXXX = Specific Device Code  
Y = Year  
M = Month  
DDD = Additional Traceability Data

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DD = Additional Traceability Data

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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